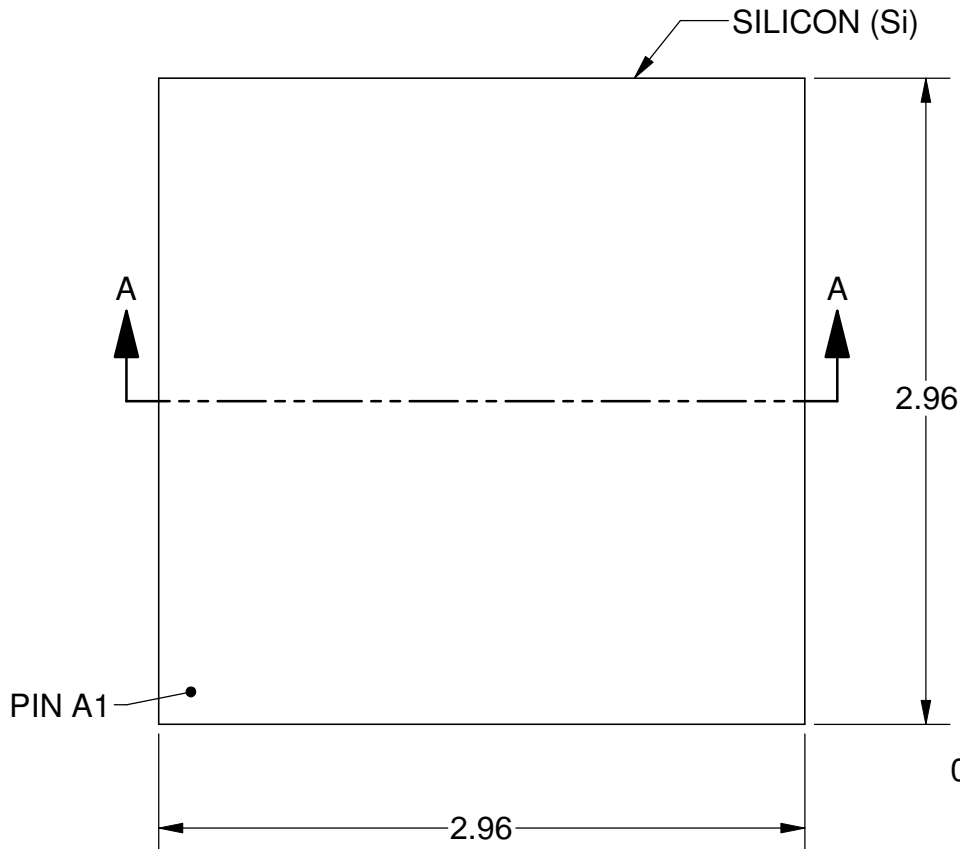
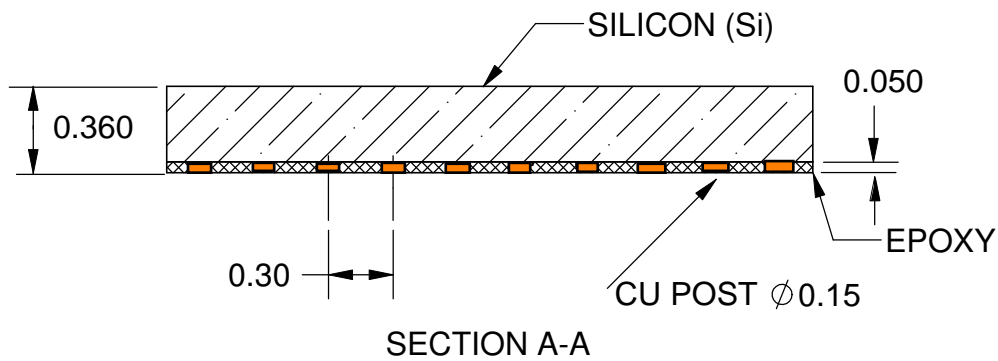
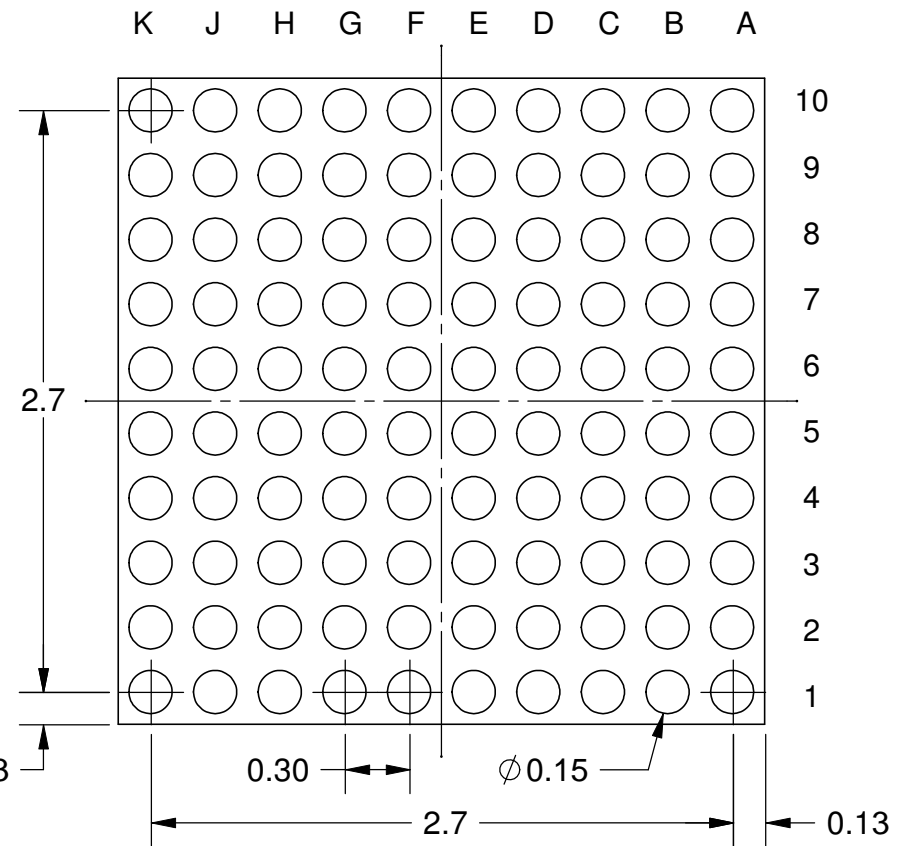


TOP VIEW




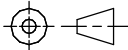
PAD VIEW



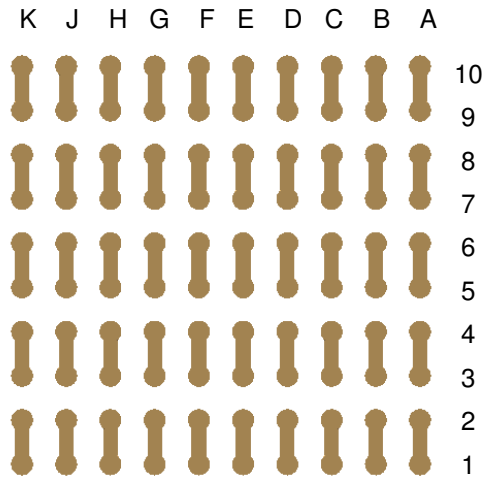
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) PAD ALLOY: Cu (50um Thick)

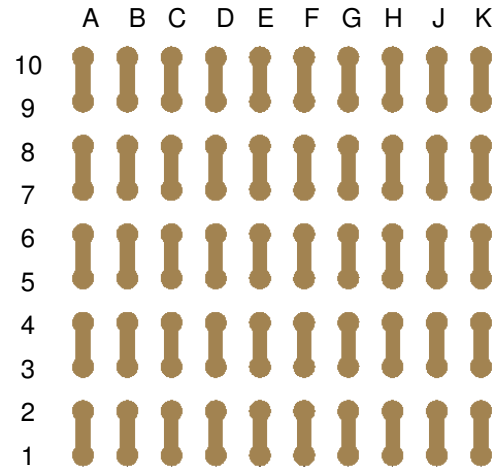
- 3) PAD Cu DIAMETER: 0.15mm.
- 4) DIE MATERIAL: Si (SILICON).
- 5) DAISY CHAIN PATTERN (SEE PAGE 2).

TOLERANCE UNLESS NOTED		APPROVALS	DATE				
X.X	+/- 0.3	DRAWN J. Hines	12/29/2010				
X.XX	+/- 0.03						
X.XXX	+/- 0.003			ENG	MFG	SCALE 28.5:1	SIZE A
ALL DIMENSIONS IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA					
THIRD ANGLE PROJECTION		CUST					
		REVISED		DO NOT SCALE DRAWING			

BALL VIEW

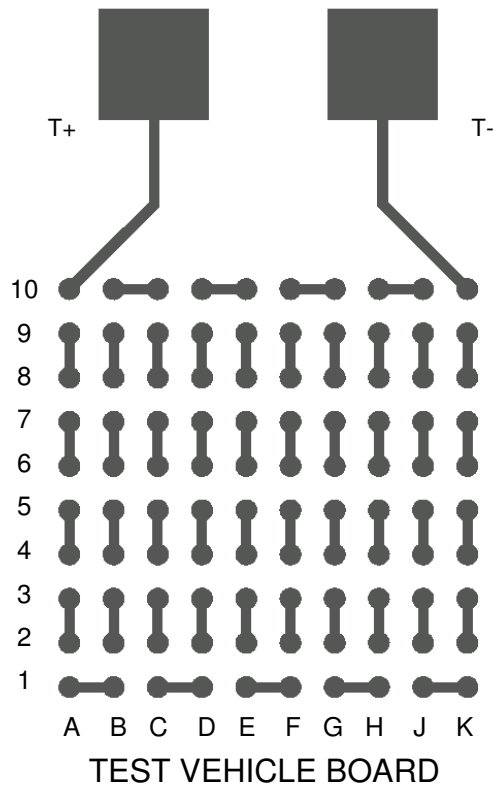


DAISY CHAIN PATTERN

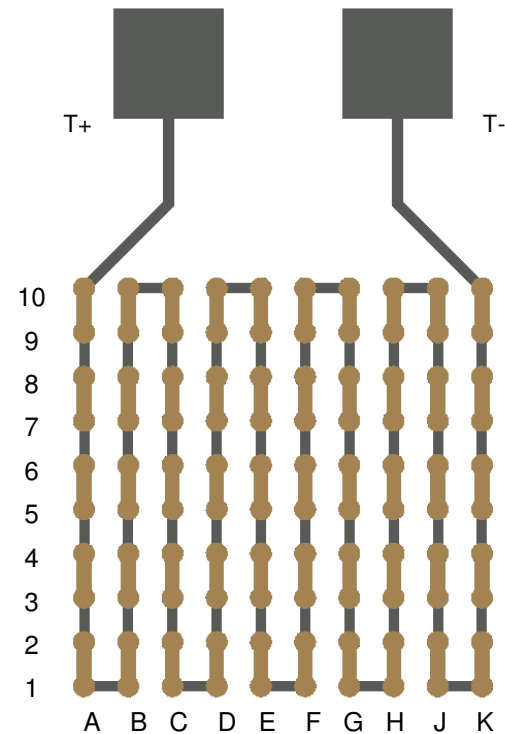


BOTTOM SIDE
(TOP X-RAY VIEW)

TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine ®			
TITLE eWLP100T.3-DC108D3 100-L P=0.3mm (TEG0306)			
SCALE 19.5:1	SIZE A	DRAWING NO. 731080	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	